



Connectors > Socket Connectors > IC Sockets > LGA Sockets



IC Socket Type: **LGA 3647**

Number of Positions: **1824**

Contact Mating Area Plating Material Thickness: **.76 μm [30 μin]**

Centerline (Pitch): **.86 mm, .99 mm [.034 in, .039 in]**

Termination Method to PCB: **Surface Mount - Solder Ball**

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board

Configuration Features

Number of Positions	1824
Grid Spacing	.9906 x .8585 mm [.039 x .0338 in]

Body Features

Frame Style	C Shape
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Contact Features

Contact Mating Area Plating Material	Gold (Au)
Contact Base Material	Copper Alloy
IC Socket Type	LGA 3647
Contact Mating Area Plating Material Thickness	.76 μm [30 μin]
Contact Current Rating (Max)	.5 A

Termination Features

Termination Method to PCB	Surface Mount - Solder Ball
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Mechanical Attachment

Connector Mounting Type	Board Mount
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Housing Features



Housing Color	Black
Housing Material	High Temperature Thermoplastic
Centerline (Pitch)	.86 mm, .99 mm [.034 in][.039 in]

Operation/Application

Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Tray Color	Black
Packaging Method	Tray

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	有害物质含量符合标准要求 No Restricted Substance(s) Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2025 (250) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought





Documents

Product Drawings

LEFT SIDE LGA3647-0 SOCKET-P0 FOR ODM

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_2-2129710-5_C.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2-2129710-5_C.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2-2129710-5_C.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

LGA 3647 Socket Product Flyer

English

Product Specifications

Application Specification

English